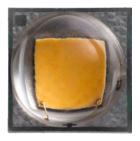


Cree® XLamp® XP-G2 LEDs



PRODUCT DESCRIPTION

The XLamp XP-G2 LED builds on the unprecedented performance of the original XP-G by increasing lumen output up to 20% while providing a single die LED point source for precise optical control. The XP-G2 LED shares the same footprint as the original XP-G, providing a seamless upgrade path and shortening the design cycle.

XLamp XP-G2 LEDs are the ideal choice for lighting applications where high light output and maximum efficacy are required, such as LED light bulbs, outdoor lighting, portable lighting, indoor lighting and solar-powered lighting.

FEATURES

- Available in white, outdoor white and 80-, 85- and 90-CRI white
- ANSI-compatible chromaticity bins
- Binned at 85 °C
- Maximum drive current:
 1500 mA
- Low thermal resistance: 4 °C/W
- Wide viewing angle: 115°
- Unlimited floor life at
 ≤ 30 °C/85% RH
- Reflow solderable JEDEC J-STD-020C
- Electrically neutral thermal path
- RoHS-compliant
- UL-recognized component (E349212)



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CHARACTERISTICS

| Characteristics | Unit | Minimum | Typical | Maximum |
|--|---------|---------|---------|---------|
| Thermal resistance, junction to solder point | °C/W | | 4 | |
| Viewing angle (FWHM) | degrees | | 115 | |
| Temperature coefficient of voltage | mV/°C | | -1.8 | |
| ESD withstand voltage (HBM per Mil-Std-883D) | V | | | 8000 |
| DC forward current | mA | | | 1500 |
| Reverse voltage | V | | | 5 |
| Forward voltage (@ 350 mA, 85 °C) | V | | 2.8 | 3.15 |
| Forward voltage (@ 700 mA, 85 °C) | V | | 2.9 | |
| Forward voltage (@ 1000 mA, 85 °C) | V | | 3.0 | |
| Forward voltage (@ 1500 mA, 85 °C) | V | | 3.1 | |
| LED junction temperature | °C | | | 150 |



FLUX CHARACTERISTICS ($T_1 = 85$ °C)

The following table provides several base order codes for XLamp XP-G2 LEDs. It is important to note that the base order codes listed here are a subset of the total available order codes for the product family.

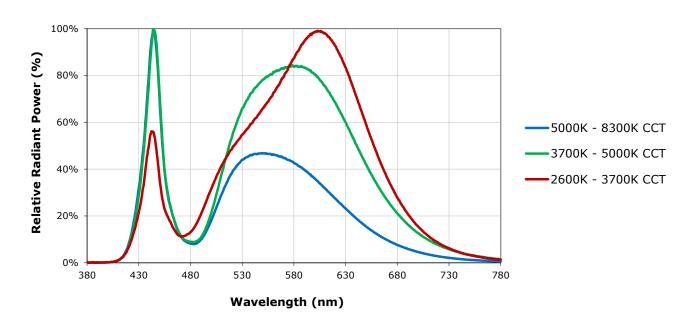
| Color | сст г | CCT Range | | Base Order Codes Min. Luminous Flux @ 350 mA | | Calculated Minimum Luminous Flux (Im)** @ 85°C | | | Oudou Codo |
|---------------|---------------|------------|-------|--|--------------------------|--|-------|----------------------|----------------------|
| Color | Min. | Max. | Group | Flux (lm) @ 85 °C | Flux (lm) @ 25 °C* | 700 mA | 1.0 A | 1.5 A | Order Code |
| | | | R3 | 122 | 138 | 223 | 297 | 402 | XPGBWT-L1-0000-00F51 |
| Cool White | 5000 K | 0 K 8300 K | R4 | 130 | 147 | 237 | 316 | 429 | XPGBWT-L1-0000-00G51 |
| | | | R5 | 139 | 158 | 254 | 338 | 458 | XPGBWT-L1-0000-00H51 |
| | | | R2 | 114 | 129 | 208 | 277 | 376 | XPGBWT-01-0000-00EC2 |
| Outdoor White | 3200 K | 5300 K | R3 | 122 | 138 | 223 | 297 | 402 | XPGBWT-01-0000-00FC2 |
| | | | R4 | 130 | 147 | 237 | 316 | 429 | XPGBWT-01-0000-00GC2 |
| | | | Q5 | 107 | 121 | 195 | 260 | 353 | XPGBWT-L1-0000-00DE4 |
| Neutral White | 3700 K | 5300 K | R2 | 114 | 129 | 208 | 277 | 376 | XPGBWT-L1-0000-00EE4 |
| | | | R3 | 122 | 138 | 223 | 297 | 402 | XPGBWT-L1-0000-00FE4 |
| | | | Q4 | 100 | 113 | 182 | 243 | 330 | XPGBWT-H1-0000-00CE7 |
| 80-CRI White | 2600 K | 4300 K | Q5 | 107 | 121 | 195 | 260 | 353 | XPGBWT-H1-0000-00DE7 |
| | | | R2 | 114 | 129 | 208 | 277 | 376 | XPGBWT-H1-0000-00EE7 |
| | | | Q4 | 100 | 113 | 182 | 243 | 330 | XPGBWT-L1-0000-00CE7 |
| Warm White | 2600 K | | Q5 | 107 | 121 | 195 | 260 | 353 | XPGBWT-L1-0000-00DE7 |
| warm winte | 2000 K | 3700 K | R2 | 114 | 129 | 208 | 277 | 376 | XPGBWT-L1-0000-00EE7 |
| | | | R3 | 122 | 138 | 223 | 297 | 402 | XPGBWT-L1-0000-00FE7 |
| OF ODIAW II | | | Р3 | 73.9 | 83.8 | 135 | 180 | 244 | XPGBWT-P1-0000-008E7 |
| | 2600 K | 2200 K | P4 | 80.6 | 91.4 | 147 | 196 | 266 | XPGBWT-P1-0000-009E7 |
| 85-CRI White | 2600 K 3200 K | Q2 | 87.4 | 99.1 | 160 | 213 | 288 | XPGBWT-P1-0000-00AE7 | |
| | | | Q3 | 93.9 | 106 | 172 | 228 | 310 | XPGBWT-P1-0000-00BE7 |
| | | | Р3 | 73.9 | 83.8 | 135 | 180 | 244 | XPGBWT-U1-0000-008E7 |
| 90-CRI White | 2600 K | 3200 K | P4 | 80.6 | 91.4 | 147 | 196 | 266 | XPGBWT-U1-0000-009E7 |
| | | Q2 | 87.4 | 99.1 | 160 | 213 | 288 | XPGBWT-U1-0000-00AE7 | |

Notes:

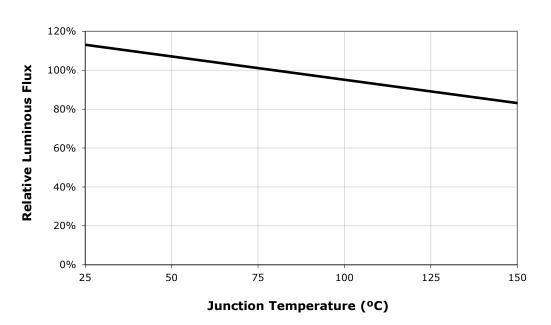
- Cree maintains a tolerance of $\pm 7\%$ on flux and power measurements, ± 0.005 on chromaticity (CCx, CCy) measurements and ± 2 on CRI measurements.
- Typical CRI for Cool White (5000 K 8300 K CCT) is 70.
- Typical CRI for Neutral White (3700 K 5300 K CCT) is 75.
- Typical CRI for Outdoor White (4000 K 5300 K CCT) is 70.
- Typical CRI for Warm White (2600 K 3700 K CCT) is 80.
- Minimum CRI for 80-CRI White is 80.
- Minimum CRI for 85-CRI White is 85.
- Minimum CRI for 90-CRI White is 90.
- * Flux values @ 25 °C are calculated and for reference only.
- ** Calculated flux values at 700 mA, 1 A and 1.5 A are for reference only.



RELATIVE SPECTRAL POWER DISTRIBUTION

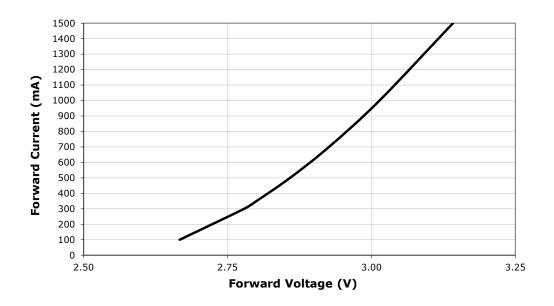


RELATIVE FLUX VS. JUNCTION TEMPERATURE ($I_F = 350 \text{ mA}$)

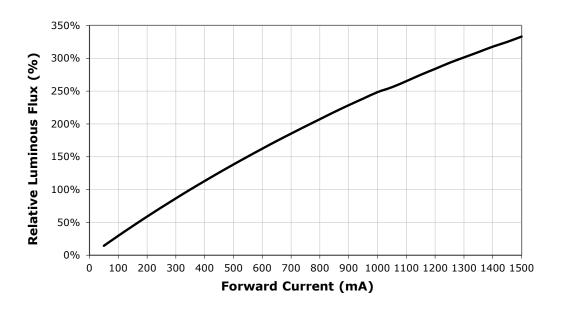




ELECTRICAL CHARACTERISTICS (T₁ = 85 °C)

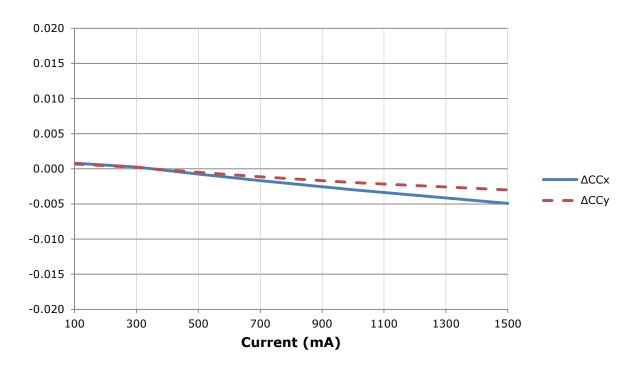


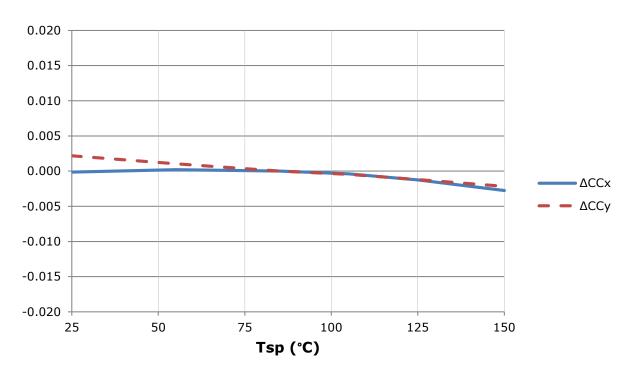
RELATIVE FLUX VS. CURRENT ($T_1 = 85$ °C)





RELATIVE CHROMATICITY VS CURRENT AND TEMPERATURE (WARM WHITE*)

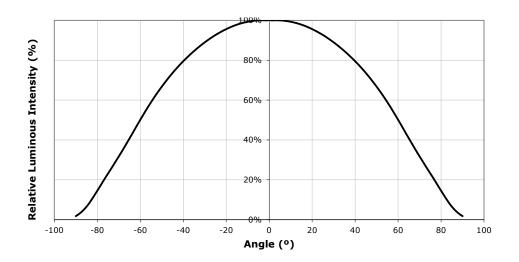




^{*} Warm White XLamp XP-G2 LEDs have a typical CRI of 80.

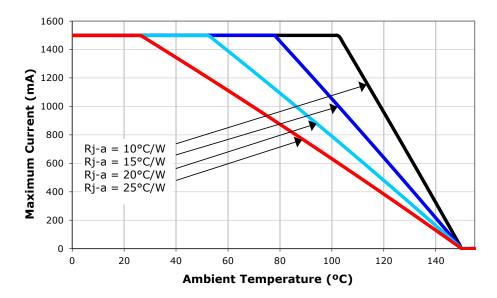


TYPICAL SPATIAL DISTRIBUTION



THERMAL DESIGN

The maximum forward current is determined by the thermal resistance between the LED junction and ambient. It is crucial for the end product to be designed in a manner that minimizes the thermal resistance from the solder point to ambient in order to optimize lamp life and optical characteristics.

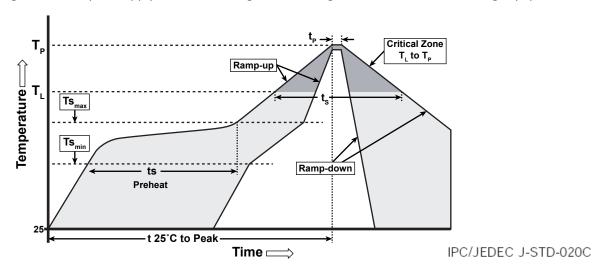




REFLOW SOLDERING CHARACTERISTICS

In testing, Cree has found XLamp XP-G2 LEDs to be compatible with JEDEC J-STD-020C, using the parameters listed below. As a general guideline, Cree recommends that users follow the recommended soldering profile provided by the manufacturer of solder paste used.

Note that this general guideline may not apply to all PCB designs and configurations of reflow soldering equipment.



| Profile Feature | Lead-Based Solder | Lead-Free Solder |
|---|-------------------|------------------|
| Average Ramp-Up Rate (Ts _{max} to Tp) | 3 °C/second max. | 3 °C/second max. |
| Preheat: Temperature Min (Ts _{min}) | 100 °C | 150 °C |
| Preheat: Temperature Max (Ts _{max}) | 150 °C | 200 °C |
| Preheat: Time (ts _{min} to ts _{max}) | 60-120 seconds | 60-180 seconds |
| Time Maintained Above: Temperature (T _L) | 183 °C | 217 °C |
| Time Maintained Above: Time (t _L) | 60-150 seconds | 60-150 seconds |
| Peak/Classification Temperature (Tp) | 215 °C | 260 °C |
| Time Within 5 °C of Actual Peak Temperature (tp) | 10-30 seconds | 20-40 seconds |
| Ramp-Down Rate | 6 °C/second max. | 6 °C/second max. |
| Time 25 °C to Peak Temperature | 6 minutes max. | 8 minutes max. |

Note: All temperatures refer to topside of the package, measured on the package body surface.



NOTES

Lumen Maintenance Projections

Cree now uses standardized IES LM-80-08 and TM-21-11 methods for collecting long-term data and extrapolating LED lumen maintenance. For information on the specific LM-80 data sets available for this LED, refer to the public LM-80 results document at www.cree.com/xlamp_app_notes/LM80_results.

Please read the XLamp Long-Term Lumen Maintenance application note at www.cree.com/xlamp_app_notes/lumen_maintenance for more details on Cree's lumen maintenance testing and forecasting. Please read the XLamp Thermal Management application note at www.cree.com/xlamp_app_notes/thermal_management for details on how thermal design, ambient temperature, and drive current affect the LED junction temperature.

Moisture Sensitivity

In testing, Cree has found XLamp XP-G2 LEDs to have unlimited floor life in conditions \leq 30 °C/85% relative humidity (RH). Moisture testing included a 168-hour soak at 85 °C/85% RH followed by 3 reflow cycles, with visual and electrical inspections at each stage.

Cree recommends keeping XLamp LEDs in their sealed moisture-barrier packaging until immediately prior to use. Cree also recommends returning any unused LEDs to the resealable moisture-barrier bag and closing the bag immediately after use.

RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Cree representative or from the Product Ecology section of www.cree.com.

UL Recognized Component

Level 4 enclosure consideration. The LED package or a portion thereof has been investigated as a fire and electrical enclosure per ANSI/UL 8750.

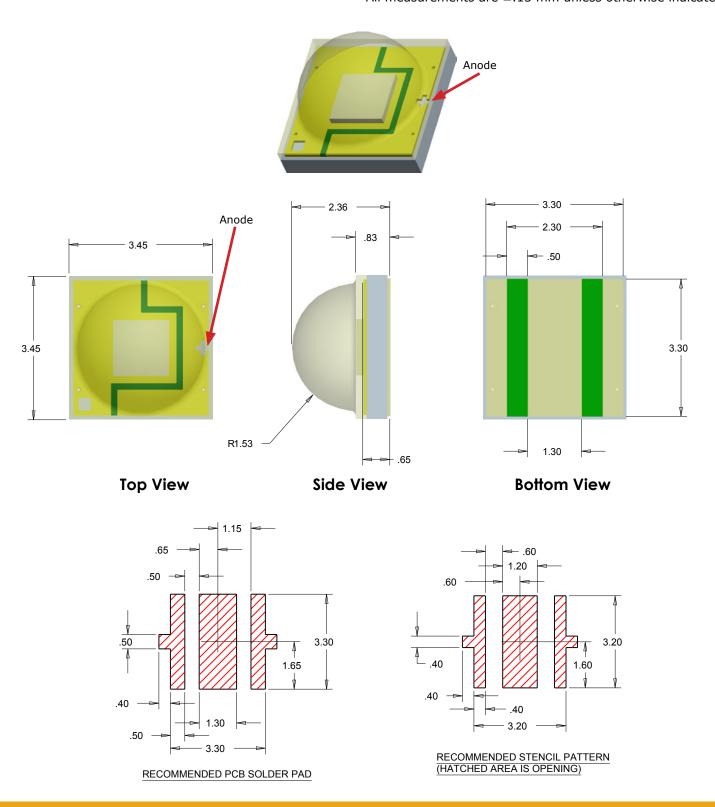
Vision Advisory Claim

WARNING: Do not look at exposed lamp in operation. Eye injury can result. See LED Eye Safety at www.cree.com/xlamp_app_notes/led_eye_safety.



MECHANICAL DIMENSIONS ($T_A = 25$ °C)

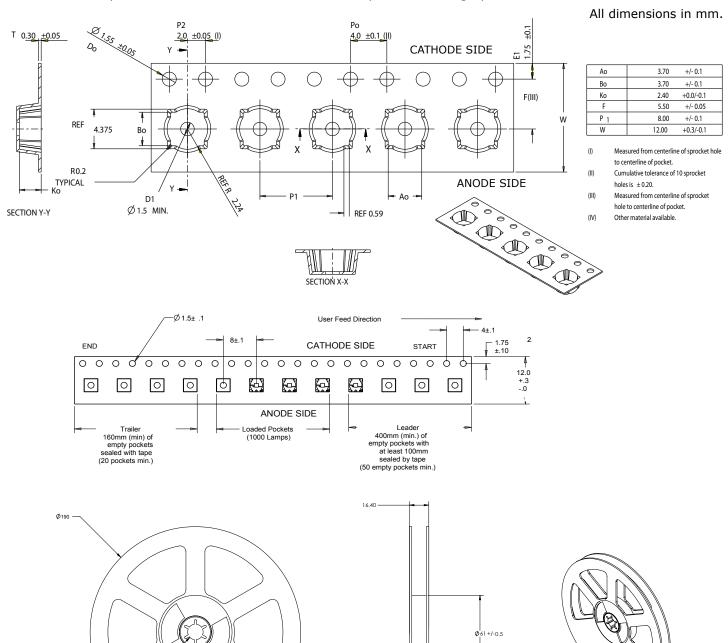
All measurements are $\pm .13$ mm unless otherwise indicated.





TAPE AND REEL

All Cree carrier tapes conform to EIA-481D, Automated Component Handling Systems Standard.



MEASURED AT INSIDE EDGE

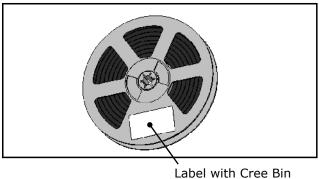
12.40^{+2.00} MEASURED AT HUB

007.5"



PACKAGING

Unpackaged Reel



Code, Qty, Reel ID

Packaged Reel

